

In the Claims:

Please cancel claims 1-80 and 86-89, amend claims 82-84, and add new claims 90-93 as follows:

1-80. (Cancelled)

81. (Original) A method of electrically isolating modules within an integrated circuit package assembly, comprising:

attaching a first and second module to a substrate having a first and opposing second side;

providing a first conductive surface having a first and opposing second side abutting the opposing second side of the substrate;

providing a dielectric layer having a first and opposing second side abutting the opposing second side of the first conductive surface;

providing a second conductive surface abutting the opposing second side of the dielectric;

conductively coupling the first conductive surface to the first module; and

conductively coupling the second conductive surface to the second module.

82. (Currently Amended) The method of claim ~~76~~ 81, further comprising encasing the assembly in a polymer.

83. (Currently Amended) The method of claim ~~76~~ 81, further comprising encasing the assembly in a ceramic.

84. (Currently Amended) The method of claim ~~76~~ 81, further comprising encasing the assembly in glass.

85. (Original) A method of electrically isolating modules within an integrated circuit package assembly, comprising:

forming a capacitor within the semiconductor package assembly, the capacitor having a first terminal and a second terminal;

coupling a first module to the first terminal of the capacitor; and

coupling a second module to the second terminal of the capacitor.

86-89. (Cancelled)

90. (New) The method of claim 85, wherein the assembly further comprises a substrate having a first side and an opposing second side, and wherein forming a capacitor within the semiconductor package assembly further comprises forming the capacitor adjacent to the first side, and attaching the first and second modules to the first side.

91. (New) The method of claim 85, wherein the assembly further comprises a substrate having a first side and an opposing second side, and wherein forming a capacitor within the semiconductor package assembly further comprises forming the capacitor adjacent to the first side, and attaching the first and second modules to the second side.

92. (New) The method of claim 85, wherein the assembly further comprises a substrate and the modules have first and opposing second sides, and further wherein forming the capacitor within the semiconductor package assembly comprises forming the capacitor proximate to the opposing second sides of the modules.

93. (New) The method of claim 85, wherein the assembly further comprises a first and a second substrate, the first module being attached to the first substrate and the second module being attached to the second substrate, and wherein forming the capacitor within the semiconductor package assembly further comprises forming the capacitor between the first module and the second module.